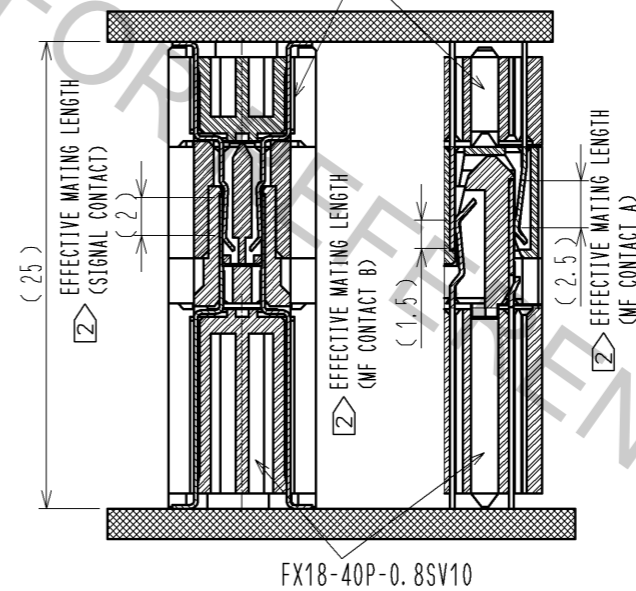
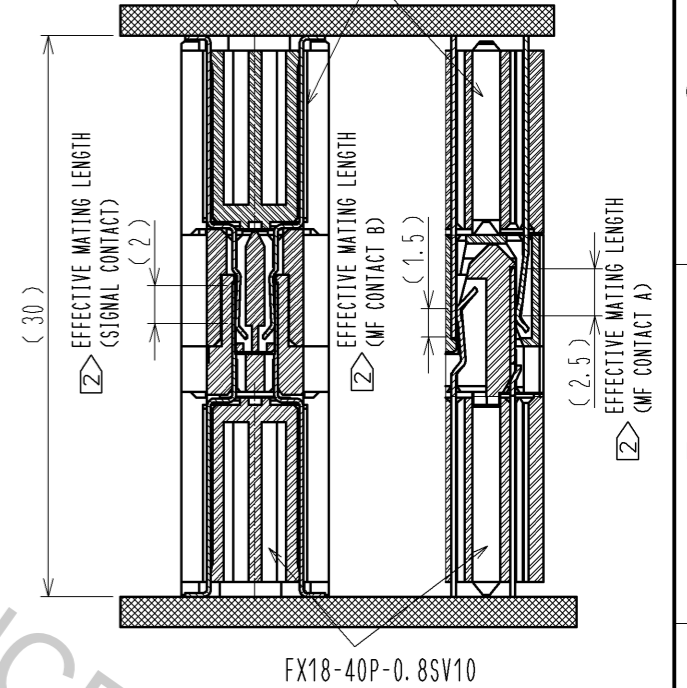


CROSS SECTION OF MATING(FREE) STACKING HEIGHT=25mm FX18-40S-0.8SV15



CROSS SECTION OF MATING(FREE) STACKING HEIGHT=30mm FX18-40S-0.8SV20



NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.

2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.

3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)

4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)

REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.

5 THIS IS PACKAGED IN TRAY. (60pcs/TRAY)

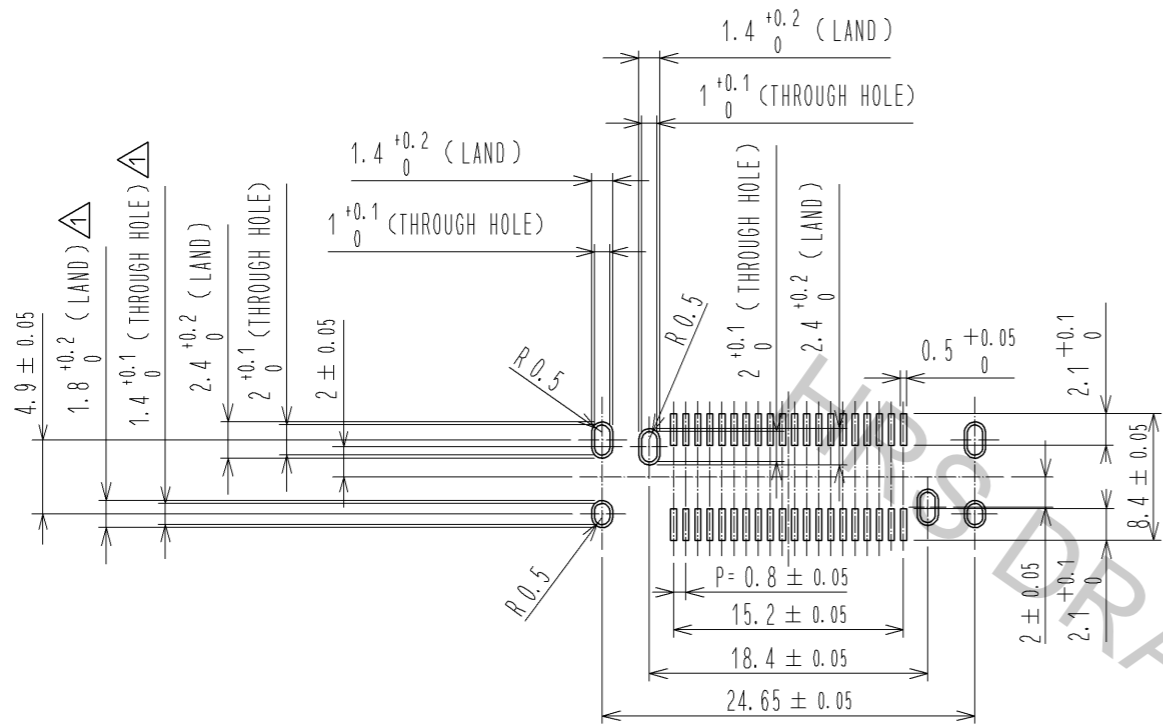
6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.

7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK UL94V-0	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE	BLACK UL94V-0			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS

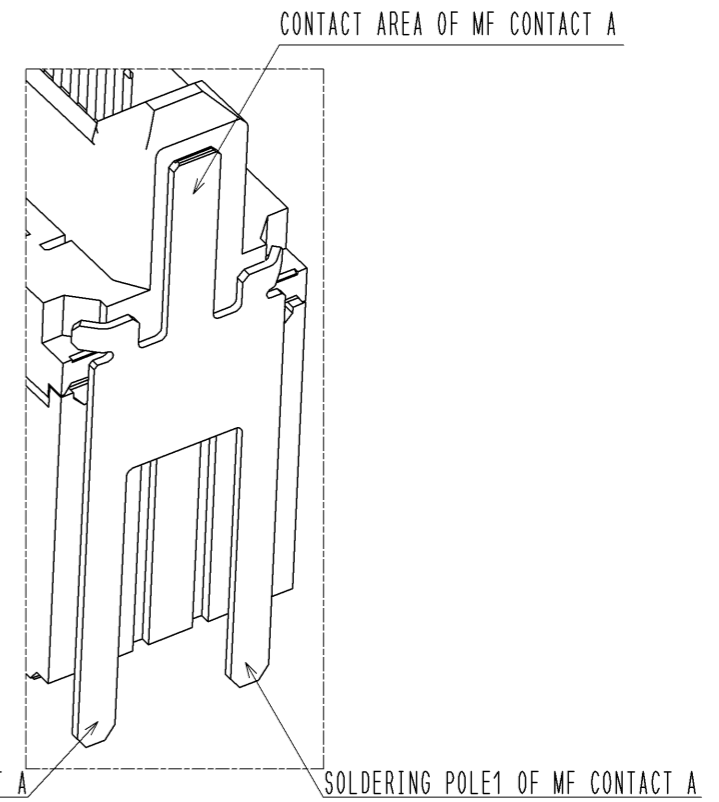
UNITS mm		SCALE 2 : 1	COUNT 3	DESCRIPTION OF REVISIONS DIS-F-00578	DESIGNED TH. SANO	CHECKED KI. HIROKAWA	DATE 11.07.21
APPROVED : HS. OKAWA 11.03.18				DRAWING NO. EDC3-334382-00			
CHECKED : KI. HIROKAWA 11.03.18				PART NO. FX18-40P-0.8SV10			
DESIGNED : TH. SANO 11.03.18				CODE NO. CL579-0022-2-00			
DRAWN : TH. SANO 11.03.18							

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
 (PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

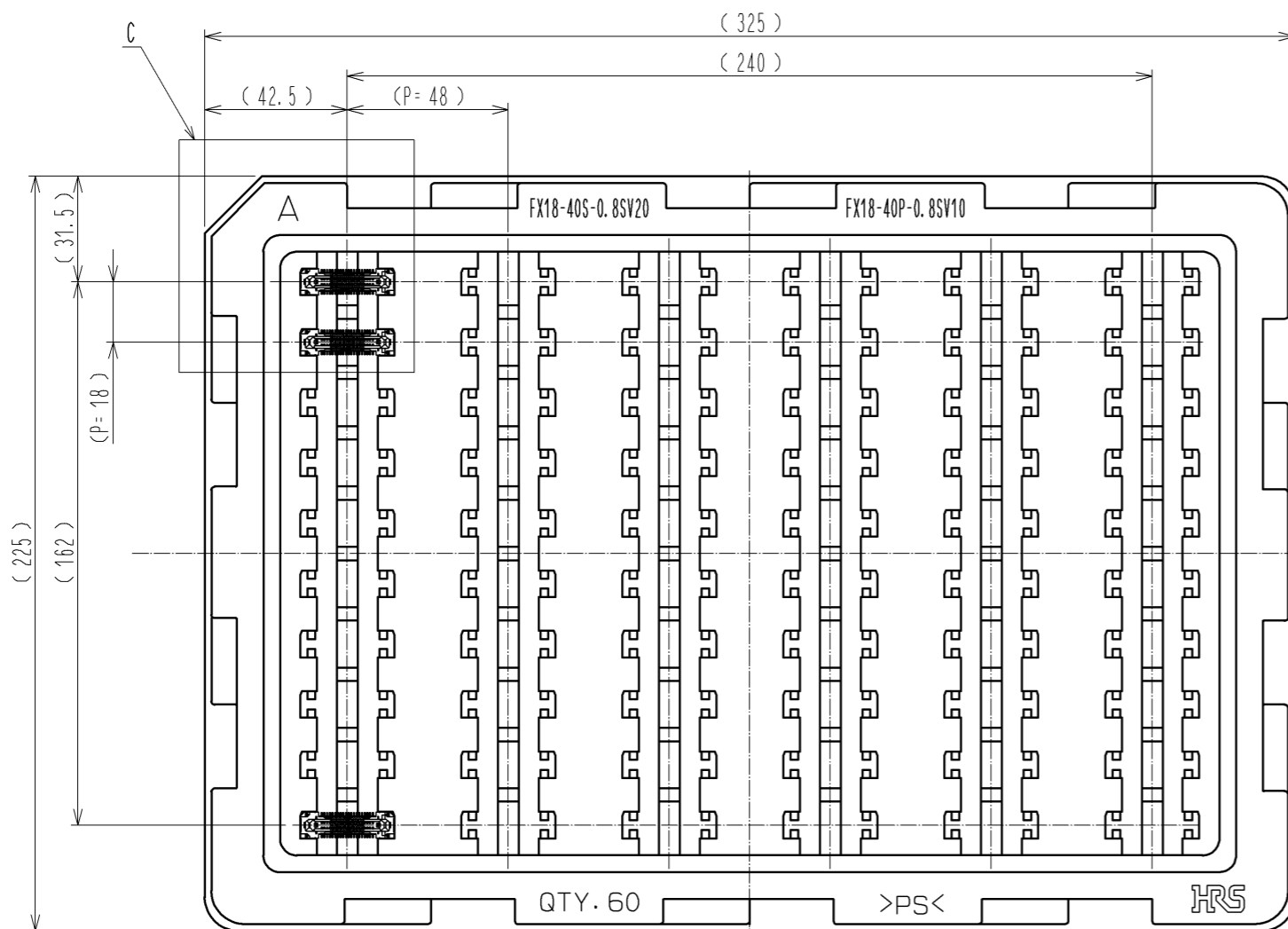


5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.  
 BE SURE TO CONNECT TO THE SAME CIRCUIT.

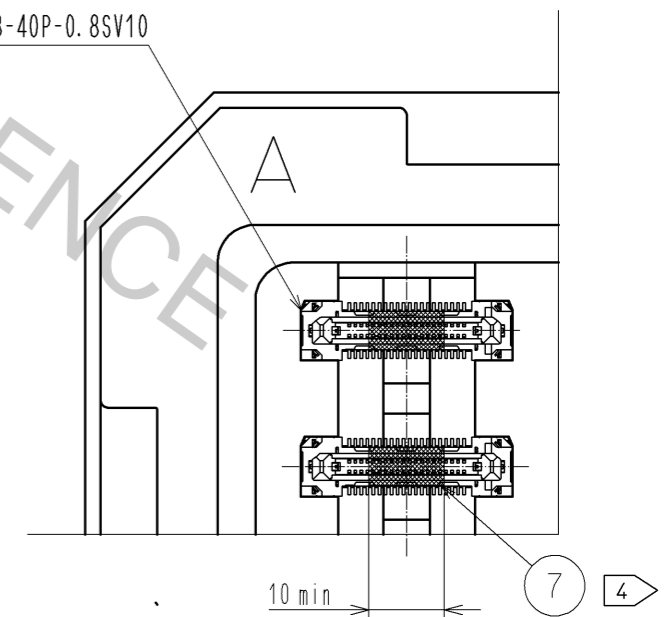


6

REFERENCE

FX18-40P-0.8SV10

C(1:1)



<b>HRS</b>	DRAWING NO.	EDC3-334382-00	2/2
	PART NO.	FX18-40P-0.8SV10	
	CODE NO.	CL579-0022-2-00	